Product Change Notification

Change Notification #:	**117532 - 00**
Change Title:	**Select Arria and Stratix FPGA Products, PCN 117532-00, Product Discontinuance, End of Life**
Date of Publication:	**April 1, 2020**

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Last Product Discontinuance Order Date:	September 30, 2020
Orders are Non-Cancelable and Non-Returnable After:	September 30, 2020
Last Product Discontinuance Shipment Date:	March 30, 2021

Description of Change to the Customer:

Intel is discontinuing part numbers with leaded solder balls as 2nd level interconnect and eutectic Tin-Lead bumps for 1st level interconnect for the following Field Programmable Gate Array (FPGA) Flip Chip product families:

- Arria II and V
- Stratix III, IV and V

This is the same discontinuance notice described in PDN2009 issued on March 30, 2020.

Reason for Change:

The Arria II & V and Stratix III, IV & V product families are being discontinued due to Intel's vendor phasing out its production line capacity for flip chip eutectic tin-lead bumps as 1st level interconnect and leaded solder balls as 2nd level interconnect.

Customer Impact of Change and Recommended Action:

Customers are advised to migrate to part numbers designated with a "G" suffix or perform a last time buy on products impacted by this discontinuance notice.

Parts with "G" suffix are fully leadfree on both 1st and 2nd level interconnects.

Products Affected / Intel Ordering Codes:

The list of affected Ordering Part Numbers (OPNs) can be downloaded here:
https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/pdn2009-opn-list.xlsx

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 1, 2020	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
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